STRIVE FOR EXCELLENCE

Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	**: Required Field*	

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-11-18
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this Form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by
Antonella Lanzafame
Date: 2024.11.18
10:59:31 CET

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STGAP3SXI	9JY7*MY3FAAA	A	Z4DA	2024-11-18
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	400	mg	Each	ECOPACK® 3
Identity	**Authority**			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape	
QFP	10.38x7.55	16	gull wing	
Comment				
Comment	Y7 SO 16 .30 LARGE JEDEC MS-013			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	**Description**	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	**Description**	

QueryList : California Prop65 list, dated 17th Nov 2023			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	**amount in product (mg)**	**Application**	**ppm in product**
Nickel	0.011	alloy	28

QueryList :Customer	Response
QUERY	**Response**

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				Response
QUERY				**Response**
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hazardous substance				
Lead (Pb)	**Cadmium (Cd)**	**Mercury (Hg)**	**Hexavalent Chromium (Cr VI)**	**PBB & PBDE**
O	O	O	O	O

QueryList : REACH-27th June 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material

QueryList : Responsible metals sourcing	**Response**
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	**Cobalt, Gold, Tantalum, Tin, Tungsten,**

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	**Response**
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	**Response**
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	**Response**
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	**Response**
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	**Response**
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	**Response**
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	**Response**
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	**Response**
Product does not contain Phenol, isopropylated, phosphate (3:1)	True

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**9JY7*MY3FAAA**		400.0005		7000002.0	1000016.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Dies	M-011 Other inorganic materials	0.417	mg	supplier	die	Silicon(Si)	7440-21-3		0.035	mg	83933	88
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.015	mg	35971	38
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.002	mg	4796	5
				supplier	metallisation	Copper(Cu)	7440-50-8		0.219	mg	525180	548
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.001	mg	2398	3
				supplier	metallisation	Gold(Au)	7440-57-5		0.006	mg	14388	15
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.011	mg	26379	28
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.012	mg	28777	30
				supplier	metallisation	Tungsten(W)	7440-33-7		0.022	mg	52758	55
				supplier	metallisation	Vanadium(V)	7440-62-2		0.001	mg	2398	3
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.020	mg	47962	50
				supplier	passivation	Silicon oxide	7631-86-9		0.073	mg	175060	183
Leadframe	M-004 Copper and its alloys	44.076	mg	supplier	alloy	Copper(Cu)	7440-50-8		41.384	mg	938924	103460
				supplier	alloy	Iron (Fe)	7439-89-6		1.021	mg	23165	2553
				supplier	alloy	Phosphorus(P)	7723-14-0		0.043	mg	976	108
				supplier	alloy	Zinc(Zn)	7440-66-6		0.085	mg	1928	213
				supplier	alloy	Silver (Ag)	7440-22-4		1.543	mg	35008	3858
Die attach	M-011 Other inorganic materials	0.456	mg	supplier	glue	Silver(Ag)	7440-22-4		0.256	mg	561404	640
				supplier	glue	Bisphenol A Diacrylate	Proprietary		0.027	mg	59211	68
				supplier	glue	Dicyclopentenyl group containing Acrylate	Proprietary		0.017	mg	37281	43
				supplier	glue	Butadiene copolymer	Proprietary		0.003	mg	6579	8
				supplier	glue	Polybutadiene epoxidized derivative	Proprietary		0.018	mg	39474	45
				supplier	glue	Cresol Novolac Epoxy Resins	29690-82-2		0.007	mg	15351	18
				supplier	glue	Peroxy Ketals	Proprietary		0.002	mg	4386	5
				supplier	glue	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.002	mg	4386	5
				supplier	glue	Methacrylate multialkoxysubstitutedalkyl ester	Proprietary		0.002	mg	4386	5
				supplier	glue	Silver(Ag)	7440-22-4		0.103	mg	225877	258
				supplier	glue	Bisphenol A Diacrylate	Proprietary		0.011	mg	24123	28
				supplier	glue	Dicyclopentenyl group containing Acrylate	Proprietary		0.007	mg	15351	18
				supplier	glue	Butadiene copolymer	Proprietary		0.001	mg	2193	3
Die attach 2		0.013	mg	supplier	glue	Polybutadiene epoxidized derivative	Proprietary		0.007	mg	538462	18
				supplier	glue	Cresol Novolac Epoxy Resins	29690-82-2		0.003	mg	230769	8
				supplier	glue	Peroxy Ketals	Proprietary		0.001	mg	76923	3
				supplier	glue	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.001	mg	76923	3
				supplier	glue	Methacrylate multialkoxysubstitutedalkyl ester	Proprietary		0.001	mg	76923	3
Bonding wires	M-008 Precious metals	0.244	mg	supplier	wire	Gold (Au)	7440-57-5		0.085	mg	348361	213
	M-004 Copper and its alloys			supplier	wire	Copper (Cu)	7440-50-8		0.156	mg	639344	390
	0			supplier	wire	Palladium(Pd)	7440-05-3		0.003	mg	12295	8
Encapsulation	M-011 Other inorganic materials	353.397	mg	supplier	mold compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-d	85954-11-6		5.399	mg	15277	13498
				supplier	mold compound	Epoxy Resin B	29690-82-2		5.399	mg	15277	13498
				supplier	mold compound	Phenol Resin	25068-38-6		24.115	mg	68238	60288
				supplier	mold compound	Silica(Amorphous) A	60676-86-0		281.052	mg	795287	702630
				supplier	mold compound	Silica(Amorphous) B	7631-86-9		35.632	mg	100827	89080
				supplier	mold compound	Carbon black	1333-86-4		1.800	mg	5093	4500
Connections coating	Solder	1.397	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.397	mg	1000000	3494